

The Most Accurate Manual Scribing System Available Handy Wafer Scriber



Features

- Suitable for scribing InP, Glass, GaAs, Si, SiO₂, Sapphire and SiC wafers up to 3 inches in diameter
- Predetermined scribing angle for optimal results
- Select tool. Secure wafer and scribe
- Two-part design with non-slip surface holds wafers firmly while scribing
- Unique pen design enables uniform scribing pressure

Instructions

1 Assemble

2 Sandwich wafer between plates

Wafer

3 Scribe the wafer along the guide

Scan QR code for more info
(Link to 1min video)

TECDIA Diamond Scribing Tools

